BYV430J-600P

Dual ultrafast power diode

3 May 2017 **Product data sheet**

1. General description

Dual ultrafast power diodes in a TO3PF plastic package.

2. Features and benefits

- Very low on-state loss
- Reduces switching losses in associated MOSFET or IGBT
- Low leakage current
- Isolated plastic package

3. Applications

- Active PFC in air conditioner
- S.M.P.S Power Factor Correction (PFC)
- Half-bridge / full-bridge switched-mode power supplies

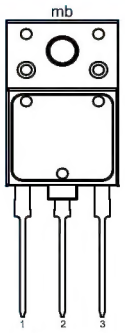
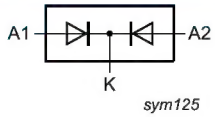
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_R	reverse voltage	DC		-	-	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $T_h \leq 64$ °C; square-wave pulse; per diode; Fig. 1; Fig. 2; Fig. 3		-	-	30	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25$ µs; square-wave pulse		-	-	60	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse; per diode; Fig. 4		-	-	180	A
		$t_p = 8.3$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse; per diode		-	-	200	A
Static characteristics							
V_F	forward voltage	$I_F = 30$ A; $T_j = 25$ °C; Fig. 6		-	1.5	2	V
		$I_F = 30$ A; $T_j = 150$ °C; Fig. 6		-	1.25	-	V
Dynamic characteristics							
t_{rr}	reverse recovery time	$I_F = 30$ A; $V_R = 30$ V; $dI_F/dt = 200$ A/µs; $T_j = 25$ °C; Fig. 7		-	53	90	ns
		$I_F = 30$ A; $V_R = 200$ V; $dI_F/dt = 200$ A/µs; $T_j = 25$ °C; Fig. 7		-	64	-	ns
		$I_F = 30$ A; $V_R = 200$ V; $dI_F/dt = 200$ A/µs; $T_j = 125$ °C; Fig. 7		-	113	-	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode 1	 TO3PF	 sym125
2	K	cathode		
3	A2	anode 2		
mb	mb	mounting base		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYV430J-600P	TO3PF	Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-3P 'full pack'	TO3PF

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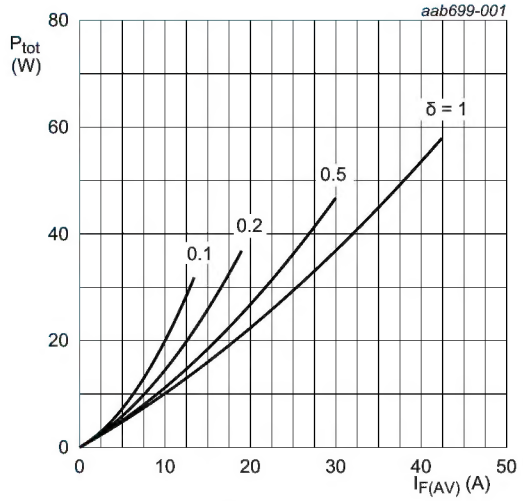
7. Limiting values

Table 4. Limiting values

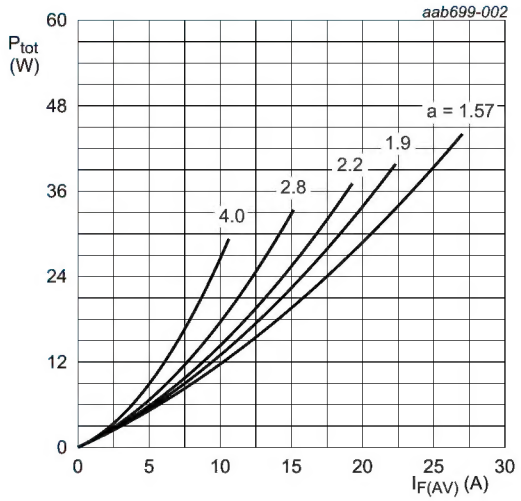
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{RRM}	repetitive peak reverse voltage			-	600	V
V_{RWM}	crest working reverse voltage			-	600	V
V_R	reverse voltage	DC		-	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $T_h \leq 64$ °C; square-wave pulse; per diode; Fig. 1; Fig. 2; Fig. 3		-	30	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25$ µs; square-wave pulse		-	60	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse; per diode; Fig. 4		-	180	A
		$t_p = 8.3$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse; per diode		-	200	A
T_{stg}	storage temperature			-55	175	°C
T_j	junction temperature			-	175	°C



$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$
$V_o = 0.899$ V; $R_s = 0.0110$ Ω

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; typical values; per diode



a = form factor = $I_{F(RMS)} / I_{F(AV)}$
$V_o = 0.899$ V; $R_s = 0.0110$ Ω

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; typical values; per diode

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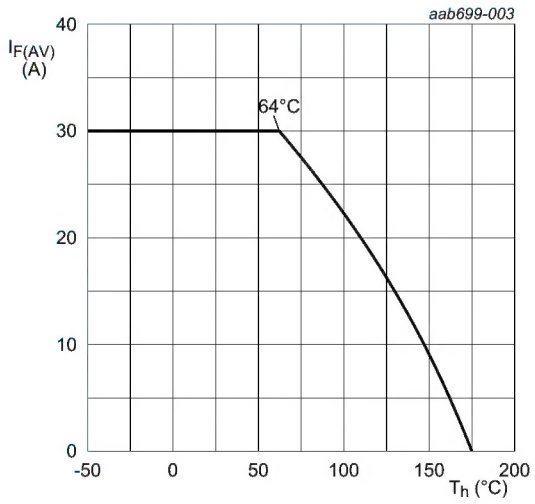

Fig. 3. Average forward current as a function of heatsink temperature; typical values; per diode

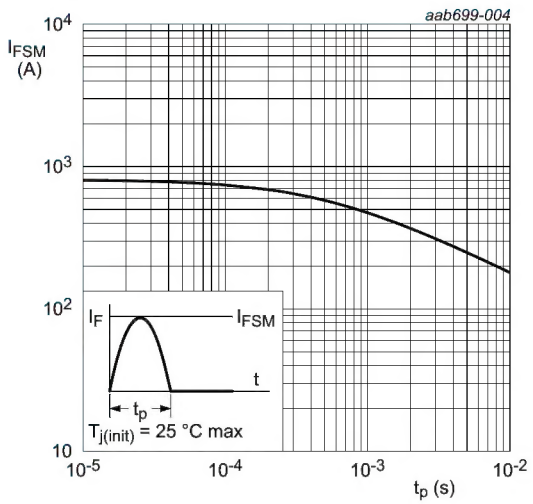

Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values; per diode

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8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-h)}$	thermal resistance from junction to heatsink	with heatsink compound; per diode; Fig. 5		-	2.4	2.7	K/W
		with heatsink compound; both diodes conducting		-	1.75	2.2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	35	-	K/W

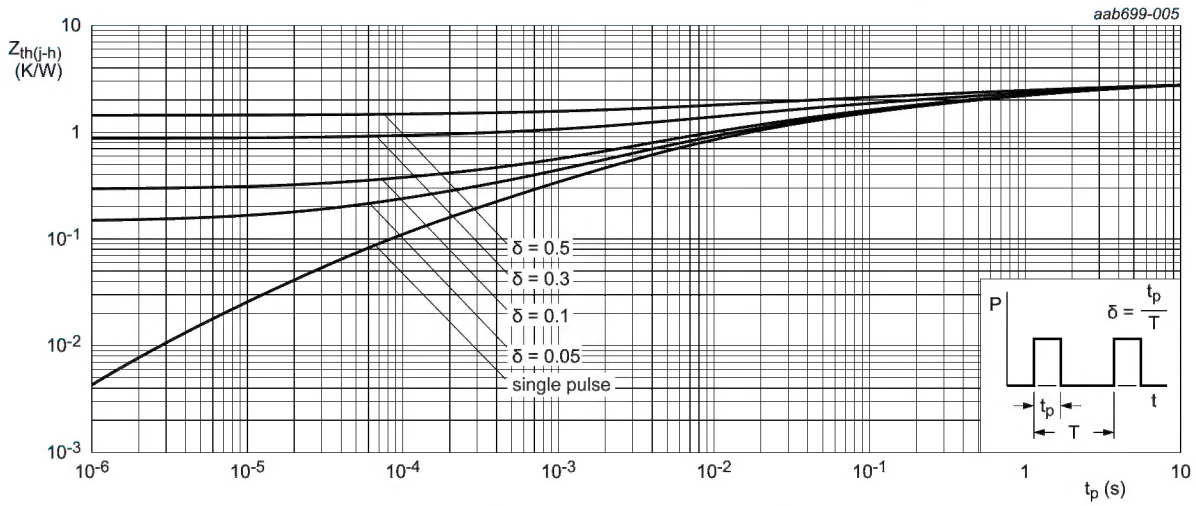

Fig. 5. Transient thermal impedance from junction to heatsink as a function of pulse duration; maximum values; per diode

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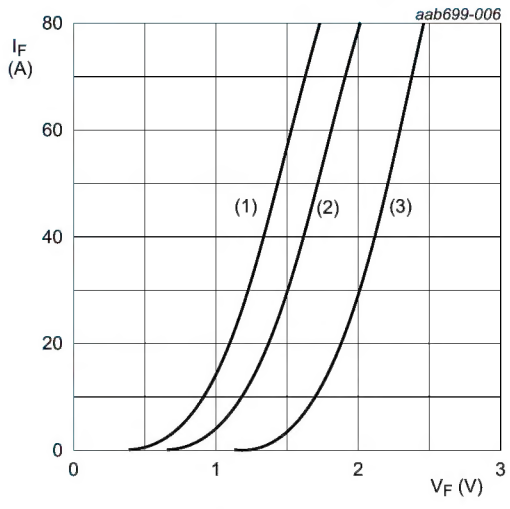
9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V_F	forward voltage	I_F = 30 A; T_j = 25 °C; Fig. 6		-	1.5	2	V
		I_F = 30 A; T_j = 150 °C; Fig. 6		-	1.25	-	V
I_R	reverse current	V_R = 600 V; T_j = 25 °C		-	-	10	µA
		V_R = 600 V; T_j = 150 °C		-	-	500	µA
Dynamic characteristics							
t_{rr}	reverse recovery time	I_F = 30 A; V_R = 30 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 7		-	53	90	ns
		I_F = 30 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 7		-	64	-	ns
		I_F = 30 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 125 °C; Fig. 7		-	113	-	ns
I_{RM}	peak reverse recovery current	I_F = 30 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 7		-	7.3	-	A
		I_F = 30 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 125 °C; Fig. 7		-	13.5	-	A
Q_r	recovered charge	I_F = 30 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 7		-	245	-	nC
		I_F = 30 A; V_R = 200 V; dI_F/dt = 200 A/µs; T_j = 125 °C; Fig. 7		-	760	-	nC



(1) T_j = 150 °C; typical values
(2) T_j = 150 °C; maximum values
(3) T_j = 25 °C; maximum values

Fig. 6. Forward current as a function of forward voltage, per diode

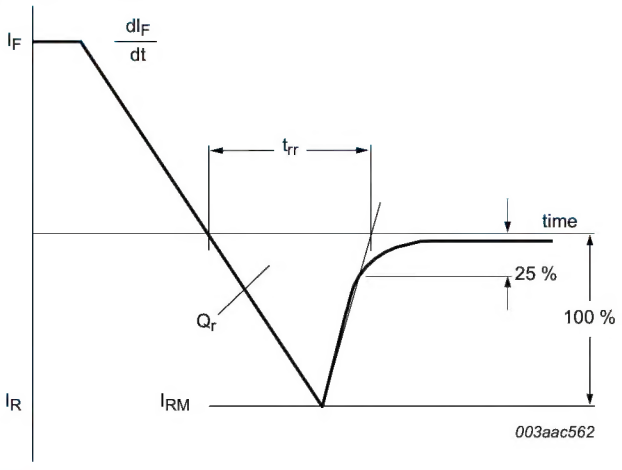


Fig. 7.

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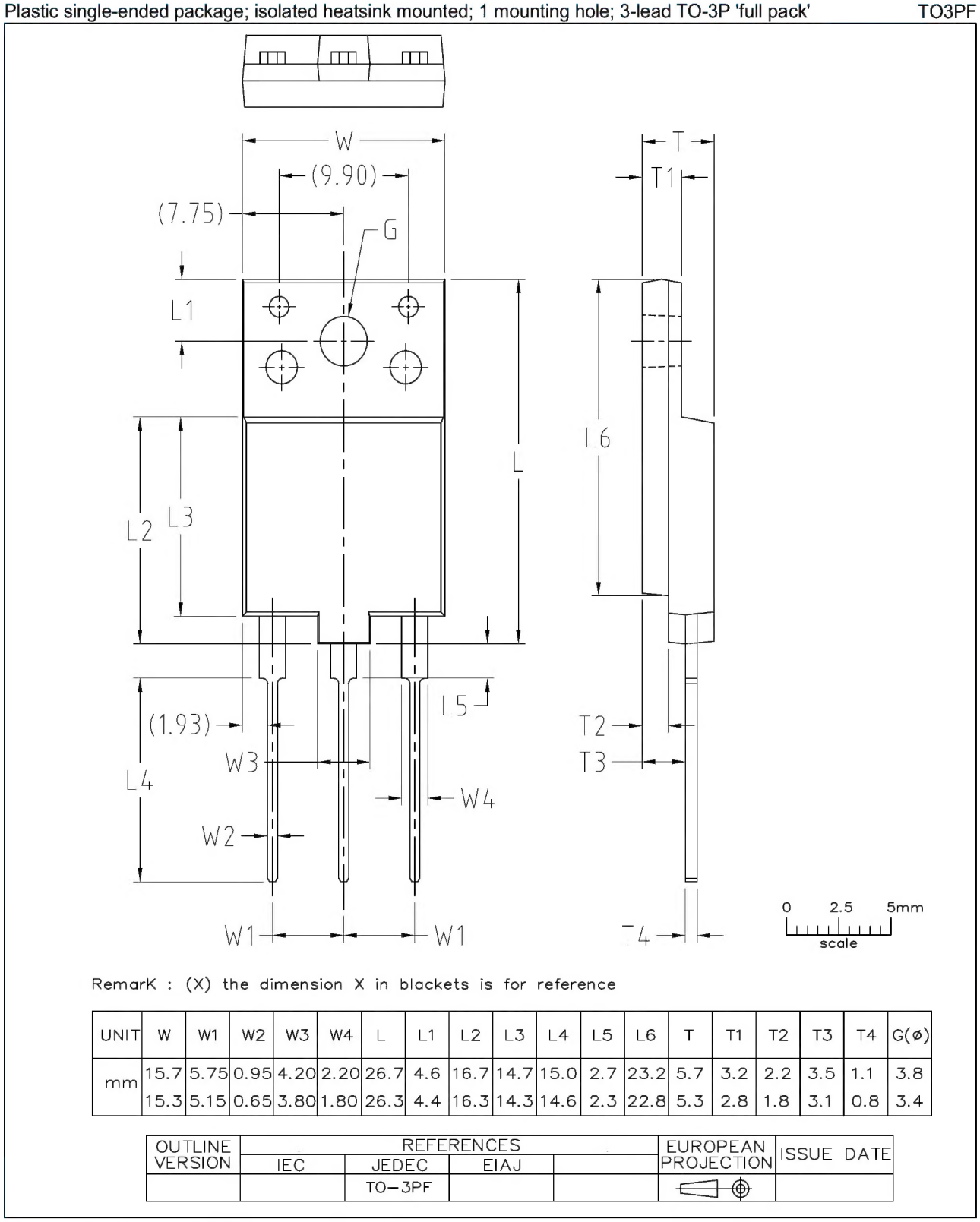
10. Package outline

Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-3P 'full pack' TO3PF



RemarK : (X) the dimension X in blackets is for reference

UNIT	W	W1	W2	W3	W4	L	L1	L2	L3	L4	L5	L6	T	T1	T2	T3	T4	G(ø)
mm	15.7	5.75	0.95	4.20	2.20	26.7	4.6	16.7	14.7	15.0	2.7	23.2	5.7	3.2	2.2	3.5	1.1	3.8
	15.3	5.15	0.65	3.80	1.80	26.3	4.4	16.3	14.3	14.6	2.3	22.8	5.3	2.8	1.8	3.1	0.8	3.4

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
		TO−3PF				

Fig. 8. Package outline TO3PF

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12. Contents

1. General description....1
2. Features and benefits....1
3. Applications....1
4. Quick reference data....1
5. Pinning information....2
6. Ordering information....2
7. Limiting values....3
8. Thermal characteristics....5
9. Characteristics....6
10. Package outline....7
11. Legal information....8

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